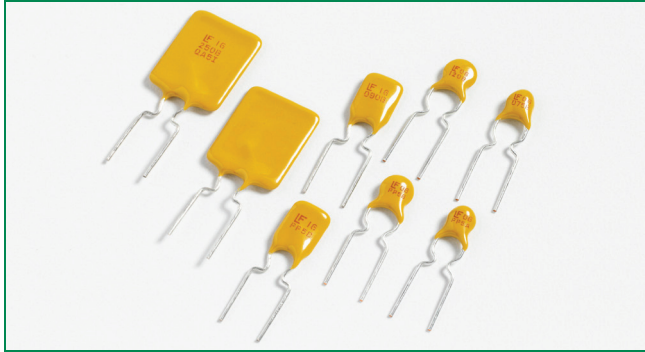




Description

- The USBR Series radial leaded device is designed to provide overcurrent protection for USB applications where space is not a concern.

Features

- RoHS compliant and lead-free
- Fast time-to-trip
- Meets all USB protection requirements
- 40A short circuit rating
- Operating voltages of 6-16V

Applications

- Computers & peripherals
- Any USB application

Agency Approvals

AGENCY AGENCY FILE NUMBER



E183209



R50119318

Electrical Characteristics

Part Number	I_{hold} (A)	I_{trip} (A)	V_{max} (Vdc)	I_{max} (A)	P_d max. (W)	Maximum Time To Trip		Resistance		Agency Approvals	
						Current (A)	Time (Sec.)	R_{min} (Ω)	R_{1max} (Ω)		
06R075B	0.75	1.30	6	40	0.3	8.00	0.4	0.100	0.230	X	X
06R120B	1.20	2.00	6	40	0.6	8.00	0.5	0.065	0.140	X	X
06R155B	1.55	2.70	6	40	0.6	7.75	2.2	0.040	0.100	X	X
16R090B	0.90	1.80	16	40	0.6	8.00	1.2	0.070	0.180	X	X
16R110B	1.10	2.20	16	40	0.7	8.00	2.3	0.050	0.140	X	X
16R135B	1.35	2.70	16	40	0.8	8.00	4.5	0.040	0.120	X	X
16R160B	1.60	3.20	16	40	0.9	8.00	9.0	0.030	0.110	X	X
16R185B	1.85	3.70	16	40	1.0	8.00	10.0	0.030	0.090	X	X
16R250B	2.50	5.00	16	40	1.2	8.00	40.0	0.020	0.060	X	X

I_{hold} = Hold current: maximum current device will pass without tripping in 20°C still air.

I_{trip} = Trip current: minimum current at which the device will trip in 20°C still air.

V_{max} = Maximum voltage device can withstand without damage at rated current (I_{max})

I_{max} = Maximum fault current device can withstand without damage at rated voltage (V_{max})

P_d = Power dissipated from device when in the tripped state at 20°C still air.

R_{min} = Minimum resistance of device in initial (un-soldered) state.

R_{typ} = Typical resistance of device in initial (un-soldered) state.

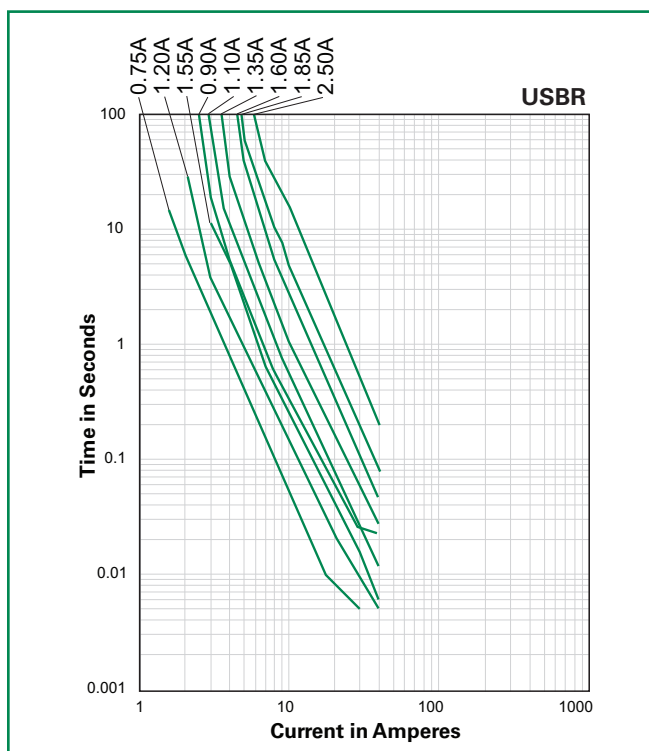
R_{1max} = Maximum resistance of device at 20°C measured one hour after tripping or reflow soldering of 260°C for 20 sec.

Caution: Operation beyond the specified rating may result in damage and possible arcing and flame.

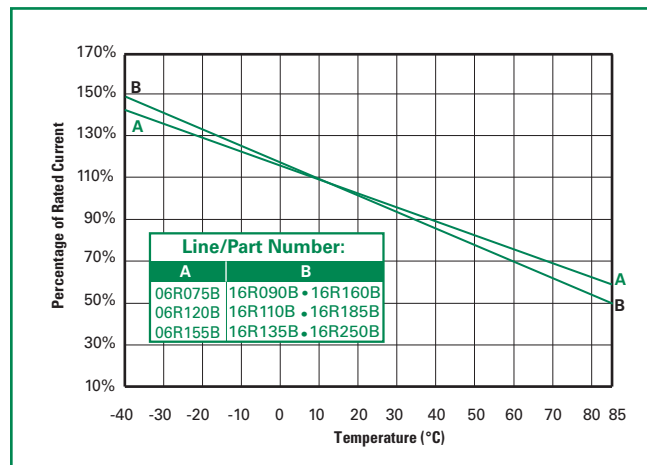
Temperature Derating

Part Number	Ambient Operation Temperature								
	-40°C	-20°C	0°C	23°C	40°C	50°C	60°C	70°C	85°C
Hold Current (A)									
06R075B	1.05	0.95	0.85	0.75	0.65	0.60	0.55	0.50	0.43
06R120B	1.69	1.52	1.36	1.20	1.04	0.96	0.88	0.80	0.68
06R155B	2.17	1.96	1.75	1.55	1.34	1.24	1.13	1.03	0.88
16R090B	1.31	1.17	1.04	0.90	0.75	0.69	0.61	0.55	0.47
16R110B	1.60	1.43	1.27	1.10	1.00	0.92	0.75	0.67	0.57
16R135B	1.96	1.76	1.55	1.35	1.12	1.04	0.92	0.82	0.70
16R160B	2.32	2.08	1.84	1.60	1.33	1.23	1.09	0.98	0.83
16R185B	2.68	2.41	2.13	1.85	1.54	1.42	1.26	1.13	0.96
16R250B	3.63	3.25	2.88	2.50	2.08	1.93	1.70	1.53	1.30

Average Time Current Curves

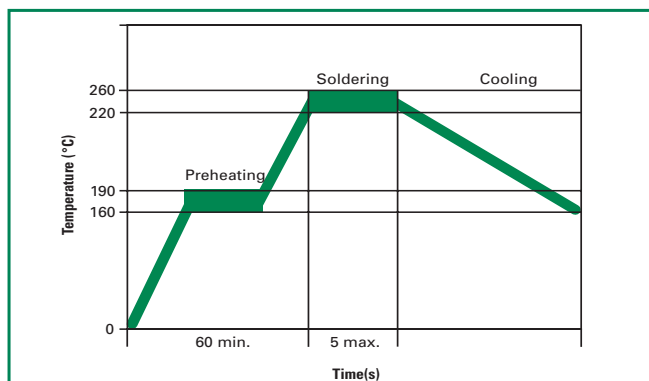


Temperature Derating Curve



The average time current curves and Temperature Derating curve performance is affected by a number of variables, and these curves provided as guidance only. Customer must verify the performance in their application.

Soldering Parameters



Pre-Heating Zone	Refer to the condition recommended by the flux manufacturer. Max. ramping rate should not exceed 4°C/Sec.
Soldering Zone	Max. solder temperature should not exceed 260°C
Cooling Zone	Cooling by natural convection in air.

Physical Specifications

Lead Material	.90-2.50A: Tin-plated Copper clad steel .75A: Tin-plated Copper
Soldering Characteristics	Solderability per MIL-STD-202, Method 208E
Insulating Material	Cured, flame retardant epoxy polymer meets UL 94V-0 requirements.
Device Labeling	Marked with 'LF', voltage, current rating, and date code.

Environmental Specifications

Operating/Storage Temperature	-40°C to +85°C
Maximum Device Surface Temperature in Tripped State	125°C
Passive Aging	+85°C, 1000 hours -/+5% typical resistance change
Humidity Aging	+85°C, 85% R.H., 1000 hours -/+5% typical resistance change
Thermal Shock	+85°C to -40°C 10 times -/+5% typical resistance change
Solvent Resistance	MIL-STD-202, Method 215F
Moisture Sensitivity Level	Level 1, J-STD-020C

Dimensions (mm)

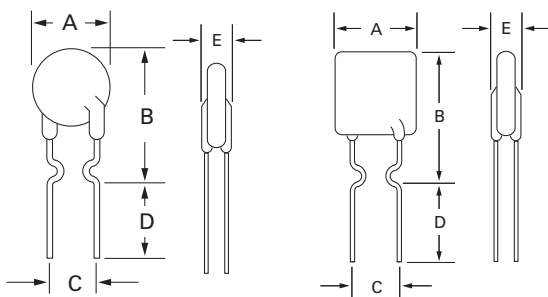
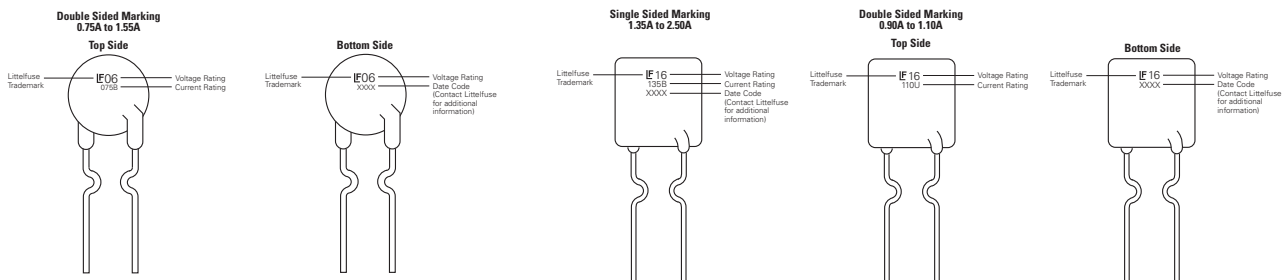


Figure 1

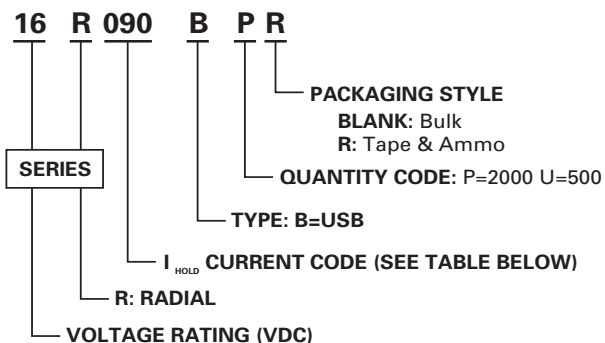
Figure 2

Part Number	Figure	A		B		C		D		E		Physical Characteristics		
		Inches	mm	Inches	mm	Inches	mm	Inches	mm	Inches	mm	Lead (dia)		Material
		Max.	Max.	Max.	Max.	Typ.	Typ.	Min.	Min.	Max.	Max.	Inches	mm	
06R075B	1	0.27	6.9	0.45	11.4	0.20	5.1	0.30	7.6	0.12	3	0.020	0.51	Sn/Cu
06R120B	1	0.27	6.9	0.46	11.7	0.20	5.1	0.30	7.6	0.12	3	0.020	0.51	Sn/CuFe
06R155B	1	0.27	6.9	0.46	11.7	0.20	5.1	0.30	7.6	0.12	3	0.020	0.51	Sn/CuFe
16R090B	2	0.29	7.4	0.48	12.2	0.20	5.1	0.30	7.6	0.12	3	0.020	0.51	Sn/CuFe
16R110B	2	0.29	7.4	0.56	14.2	0.20	5.1	0.30	7.6	0.12	3	0.020	0.51	Sn/CuFe
16R135B	2	0.35	8.9	0.53	13.5	0.20	5.1	0.30	7.6	0.12	3	0.020	0.51	Sn/CuFe
16R160B	2	0.35	8.9	0.60	15.2	0.20	5.1	0.30	7.6	0.12	3	0.020	0.51	Sn/CuFe
16R185B	2	0.40	10.2	0.62	15.7	0.20	5.1	0.30	7.6	0.12	3	0.020	0.51	Sn/CuFe
16R250B	2	0.45	11.4	0.72	18.3	0.20	5.1	0.30	7.6	0.12	3	0.020	0.51	Sn/CuFe

Part Marking System



Part Ordering Number System



Ordering Information

Part Number	Ordering Number	I _{hold} (A)	I _{hold} Code	Packaging Option	Quantity	Quantity & Packaging Codes
06R075B	06R075BU	0.75	075	Bulk	500	U
	06R075BPR			Tape and Ammo	2000	PR
06R120B	06R120BU	1.20	120	Bulk	500	U
	06R120BPR			Tape and Ammo	2000	PR
06R155B	06R155BU	1.55	155	Bulk	500	U
	06R155BPR			Tape and Ammo	2000	PR
16R090B	16R090BU	0.90	090	Bulk	500	U
	16R090BPR			Tape and Ammo	2000	PR
16R110B	16R110BU	1.10	110	Bulk	500	U
	16R110BPR			Tape and Ammo	2000	PR
16R135B	16R135BU	1.35	135	Bulk	500	U
	16R135BPR			Tape and Ammo	2000	PR
16R160B	16R160BU	1.60	160	Bulk	500	U
	16R160BPR			Tape and Ammo	2000	PR
16R185B	16R185BU	1.85	185	Bulk	500	U
	16R185BPR			Tape and Ammo	2000	PR
16R250B	16R250BU	2.50	250	Bulk	500	U
	16R250BPR			Tape and Ammo	2000	PR

Tape and Ammo Specifications

Devices taped using EIA468-B/IE286-2 standards. See table below and Figure 1 for details.

Dimension	EIA Mark	IEC Mark	Dimensions	
			Dim. (mm)	Tol. (mm)
Carrier tape width	W	W	18	-0.5 / +1.0
Hold down tape width	W₄	W₀	11	min.
Top distance between tape edges	W₆	W₂	3	max.
Sprocket hole position	W₅	W₁	9	-0.5 / +0.75
Sprocket hole diameter*	D₀	D₀	4	-/+ 0.32
Abscissa to plane(straight lead)	H	H	18.5	-/+ 3.0
Abscissa to plane(kinked lead)	H₀	H₀	16	-/+ 0.5
Abscissa to top	H₁	H₁	32.2	max.
Overall width w/o lead protrusion	C₁		42.5	max.
Overall width w/ lead protrusion	C₂		43.2	max.
Lead protrusion	L₁	L₁	1.0	max.
Protrusion of cut out	L	L	11	max.
Protrusion beyond hold-down tape	L₂	L₂	Not specified	
Sprocket hole pitch	P₀	P₀	12.7	-/+ 0.35
Pitch tolerance			20 consecutive	-/+ 1
Device pitch			12.7	
Tape thickness	t	t	0.9	max.
Tape thickness with splice	t₁		2.0	max.
Splice sprocket hole alignment			0	-/+ 0.3
Body lateral deviation	Δh	Δh	0	-/+ 1.0
Body tape plane deviation	Δp	Δp	0	-/+ 1.3
Ordinate to adjacent component lead*	P₁	P₁	3.81	-/+ 1.0
Lead spacing*	F	F	5.08	-/+ 0.8

*Differs from EIA specification.

Tape and Ammo Diagram

